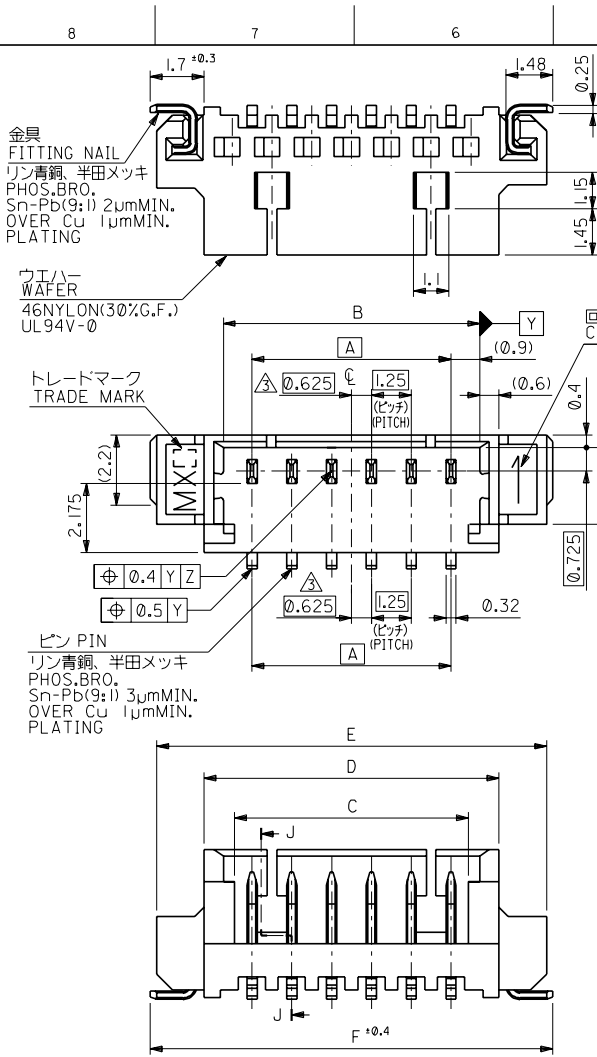
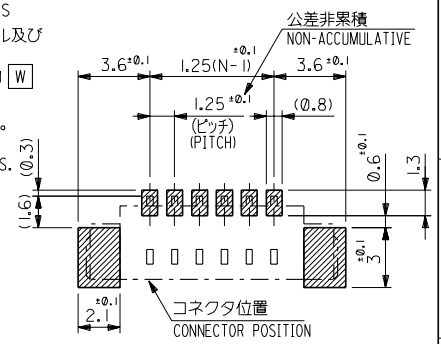


DWG. NO. SD-53398-10
DIMENSIONS IN METRIC DO NOT SCALE DRAWING



注記 NOTES

1. 嵌合相手: 51021シリーズ MATE WITH : 51021 SERIES
- △ 水平面上においての、ウェハー底面 W とソルダーテール及びフィッティングネイル底面とのズレ量を示す。
MISALIGNMENT OF SOLDER TAIL & FITTING NAIL FROM W
- △ 偶数極のみ適用。APPLY EVEN CIRCUIT PRODUCTS.
- △ ロック窓は、2、3極は1ヶ所、4極以上は2ヶ所とする。
LOCKING WINDOW : ONE PLACE FOR 2&3 CKTS.
TWO PLACES FOR MORE THAN 4 CKTS.



23.9	23.5	20.5	18.6	19.3	17.5	53398-1510	15
22.65	22.25	19.25	17.35	18.05	16.25	↑ -1410	14
21.4	21	18	16.1	16.8	15	-1310	13
20.15	19.75	16.75	14.85	15.55	13.75	-1210	12
18.9	18.5	15.5	13.6	14.3	12.5	-1110	11
17.65	17.25	14.25	12.35	13.05	11.25	-1010	10
16.4	16	13	11.1	11.8	10	-0910	9
15.15	14.75	11.75	9.85	10.55	8.75	-0810	8
13.9	13.5	10.5	8.6	9.3	7.5	-0710	7
12.65	12.25	9.25	7.35	8.05	6.25	-0610	6
11.4	11	8	6.1	6.8	5	-0510	5
10.15	9.75	6.75	4.85	5.55	3.75	-0410	4
8.9	8.5	5.5	3.6	4.3	2.5	↓ -0310	3
7.65	7.25	4.25	2.35	3.05	1.25	53398-0210	2
F	E	D	C	B	A	ENG. NO.	極数 NO. OF CKTS.

F	変更 REVISED	UC2000-0630	K.K.	M.F.	00/3/30	材料 MATERIAL 図中参照 SEE DRAWING	molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
E	変更 REVISED	UC8000-080	T.Y.	M.F.	97/7/6		
D	変更 REVISED	UC8030	H.H.	M.F.	93/10/13		
C	変更 REVISED	UC8753	K.Y.	H.H.	93/12/29		
B	変更 REVISED	UC8600	K.Y.	H.H.	93/6/18	仕上り FINISH	適用電線範囲 WIRE RANGE
A	変更 REVISED	UC8230	K.Y.	H.H.	93/3/12	被覆外径 INS. RANGE	適用電線範囲 WIRE RANGE
φ	新規作成 RELEASED	UC8942	K.Y.	H.H.	92/10/12	DRAWN BY 92/10/12	CHK'D BY 00/3/30
TR	変更内容 REVISION RECORD	DR.	DATE	DATE	DATE	APP'D BY 00/3/30	尺度 SCALE

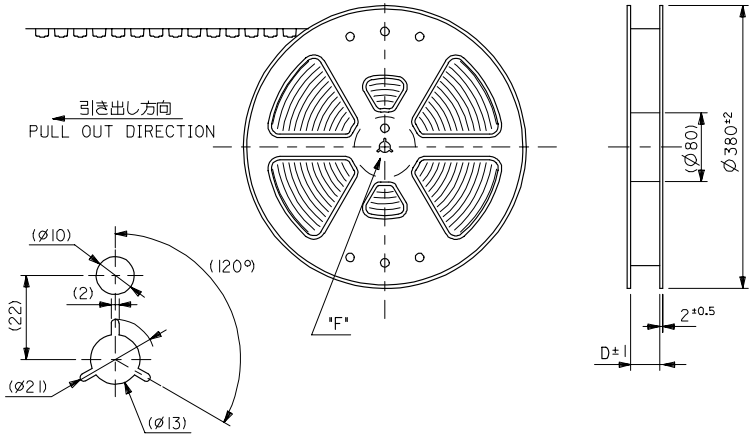
角度 ANGLE	±3°
30以上 OVER	±0.3
10以上 30 UNDER	±0.25
10 UNDER	±0.2
一般公差 GENERAL TOLERANCES	

REVISION ONLY ON CAD SYSTEM
TITLE 名称
1.25 WIRE TO BOARD CONN.
WAFER ASS'Y FOR SMT (ST.)

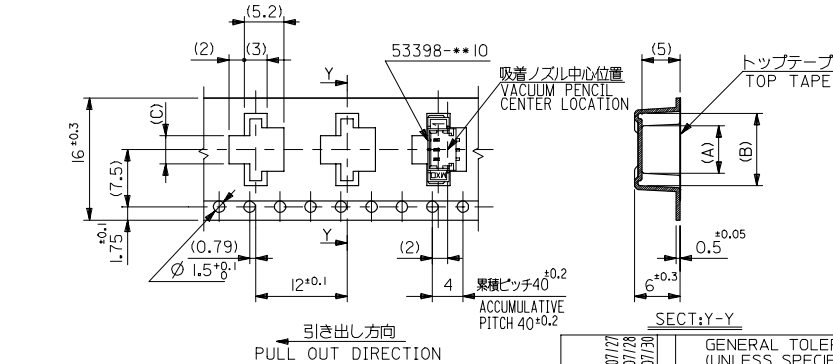
DWG. NO. SD-53398-10
REV F

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EN-01C(032)MXJ-32

10 9 8 7 6 5 4 3 2 1



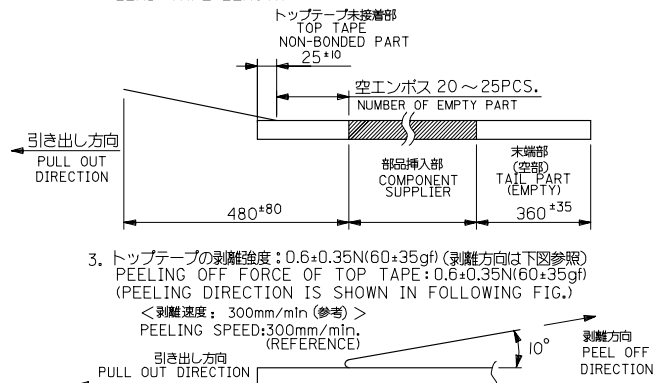
DETAIL "F"



16幅テープ (TAPE WIDTH:16)

NOTES

1. 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
2. リードテープ長さ
LEAD TAPE LENGTH



3. トッテープの剥離強度: 0.6±0.35N(60±35gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE: 0.6±0.35N(60±35gf)
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)
<剥離速度: 300mm/min (参考)>
PEELING SPEED: 300mm/min. (REFERENCE)
4. 53398-**10 の詳細寸法については図面 SD-53398-**10 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53398-**10.
5. 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トッテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

16	17.4	3.7	9.5	5.8	53398-0390	3
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	ENG. NO.	極数 CKT.
		2.45	8.25	4.55	53398-0290	2

REVISED REV	2004/07/27	2004/07/28	2004/07/28	2004/07/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	DRW: M. I. GUCH	CHK: K. ASAKAWA	APP: S. CHIKAWA	DES: S. CHIKAWA	10 UNDER	±0.2	DRAWN BY K. TOJO	DATE '93/04/13	TITLE 1.25 W/B CONN. WAFER ASS'Y FOR SMT. EMBOSSED TAPE PACKAGE		
					10 OVER 30 UNDER	±0.25	CHECKED BY YAMAGUCHI	DATE '00/12/08	MOLEX INCORPORATED		
					30 OVER	±0.3	APPROVED BY FUKUSHIMA	DATE '00/12/08	DOCUMENT NO. SD-53398-**90		
ANGULAR ±3 °					DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		SHEET NO. 1 OF 3		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

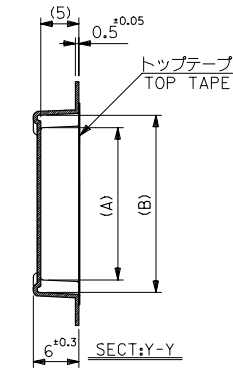
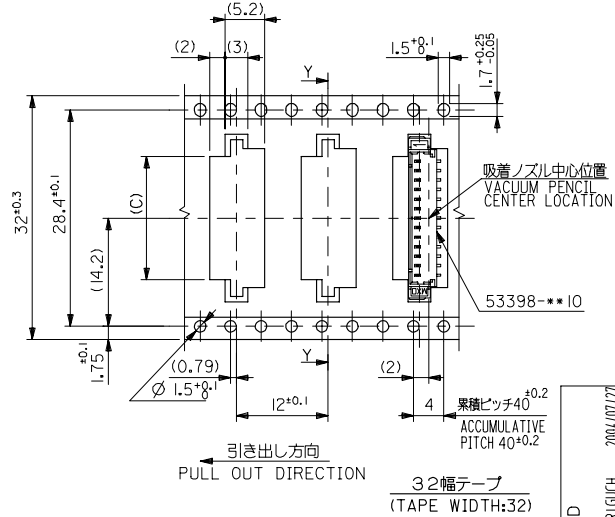
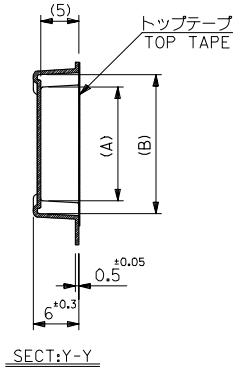
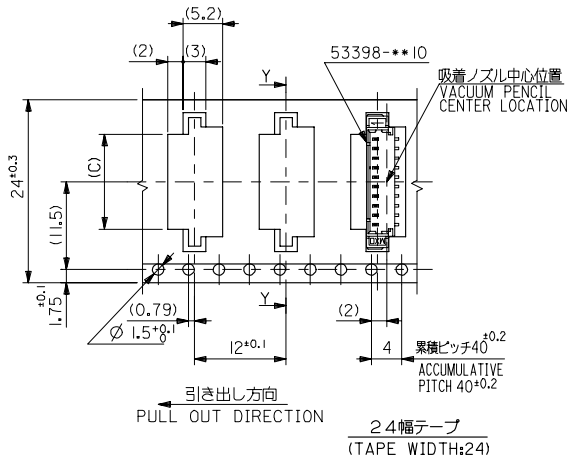
E

D

C

B

A



32	33.4	16.2	22	18.3	53398-1390	13
		14.95	20.75	17.05	-1290	12
24	25.4	13.7	19.5	15.8	-1190	11
		12.45	18.25	14.55	-1090	10
		11.2	17	13.3	-0990	9
		9.95	15.75	12.05	-0890	8
		8.7	14.5	10.8	-0790	7
		7.45	13.25	9.55	-0690	6
		6.2	12	8.3	-0590	5
		4.95	10.75	7.05	53398-0490	4
キャリアテープ幅 CARRIER TAPE WIDTH		D	(C)	(B)	(A)	ENG. NO.

REVISED REV. NO. DESCRIPTION	2004/07/27 DRAWN: RIGUCHI	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	2004/07/28 CHKD: K. ASAKAWA	10 UNDER	±0.2	DRAWN BY K. TOJO	DATE '93/04/13	TITLE 1.25 W/B CONN. WAFER ASS'Y FOR SMT. EMBOSSED TAPE PACKAGE			
	2004/07/30 APPR: S. CHIKAWA	10 OVER 30 UNDER	±0.25	CHECKED BY YAMAGUCHI	DATE '00/12/08				
		30 OVER	±0.3	APPROVED BY FUKUSHIMA	DATE '00/12/08	MATERIAL NO. SEE CHART			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3		DOCUMENT NO. SD-53398-***90		SHEET NO. 2 OF 3		

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

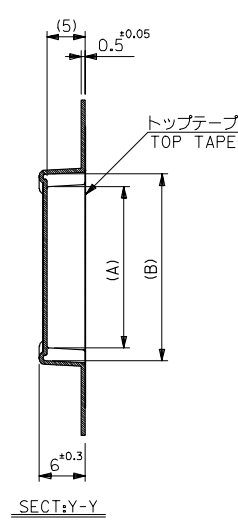
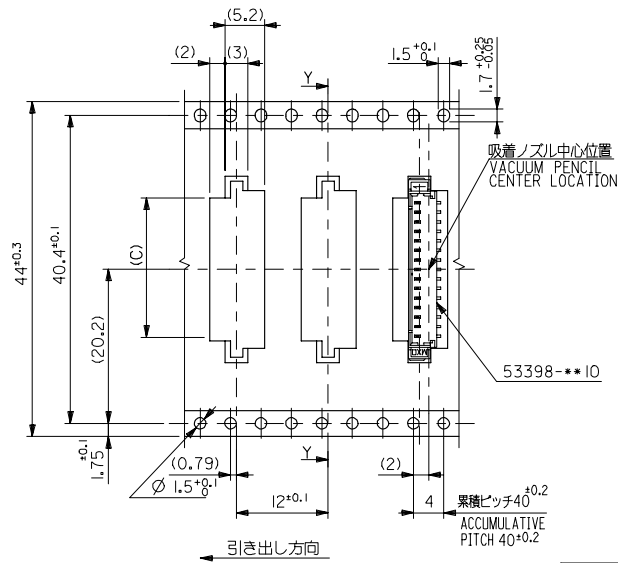
E

D

C

B

A



引き出し方向
PULL OUT DIRECTION

44幅テープ
(TAPE WIDTH:44)

44	45.4	18.7	24.5	20.8	53398-I590	I5
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	ENG. NO.	極数 CKT.
		17.45	23.25	19.55	53398-I490	I4

REVISED REV. NO. DATE DRAWN BY DATE CHKD BY DATE APPR. S. DATE DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY K. TOJO	DATE '93/04/13	TITLE 1.25 W/B CONN. WAFER ASS'Y FOR SMT. EMBOSSED TAPE PACKAGE MOLEX INCORPORATED		
	10 OVER 30 UNDER	±0.25	CHECKED BY YAMAGUCHI	DATE '00/12/08			
	30 OVER	±0.3	APPROVED BY FUKUSHIM	DATE '00/12/08			
ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART	DOCUMENT NO. SD-53398-**90	SHEET NO. 3 OF 3	

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Rev. D 2004/04/02

9 8 7 6 5 4 3 2 1 EN-02JA1021